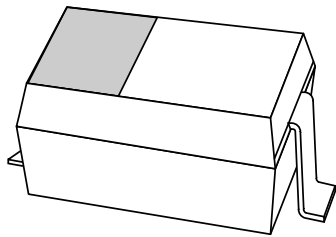


# DATA SHEET



## **PMEG2020AEA**

20 V, 2 A very low  $V_F$  MEGA  
Schottky barrier rectifier in SOD323  
(SC-76) package

# 20 V, 2 A very low $V_F$ MEGA Schottky barrier rectifier in SOD323 (SC-76) package

**PMEG2020AEA**

### FEATURES

- Forward current: 2 A
- Reverse voltage: 20 V
- Very low forward voltage
- Very small SMD package.

### APPLICATIONS

- Low voltage rectification
- High efficiency DC/DC conversion
- Switch mode power supply
- Inverse polarity protection
- Low power consumption applications.

### DESCRIPTION

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD323 (SC-76) very small SMD plastic package.

### MARKING

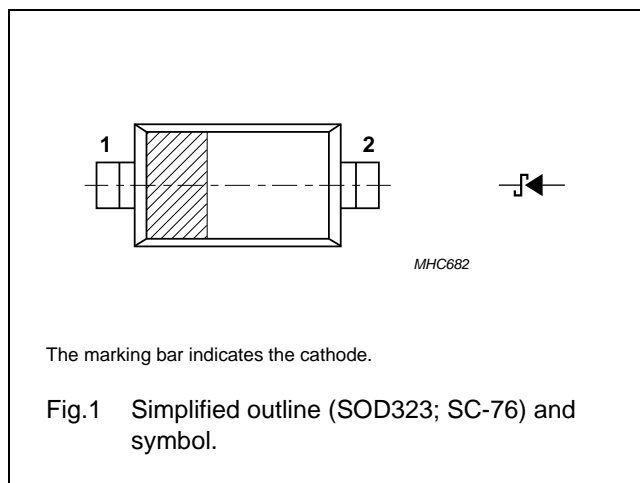
TYPE NUMBER	MARKING CODE
PMEG2020AEA	S3

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	VALUE	UNIT
$I_F$	forward current	2	A
$V_R$	reverse voltage	20	V

### PINNING

PIN	DESCRIPTION
1	cathode
2	anode



### RELATED PRODUCTS

TYPE NUMBER	DESCRIPTION	FEATURES
PMEG1020EA	2 A; 10 V ultra low $V_F$ MEGA Schottky barrier rectifier	SOD323 package; lower reverse voltage; lower forward voltage
PMEG2010EA	1 A; 20 V ultra low $V_F$ MEGA Schottky barrier rectifier	SOD323 package; lower forward current; lower reverse current and diode capacitance

### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PMEG2020AEA	-	plastic surface mounted package; 2 leads	SOD323

# 20 V, 2 A very low $V_F$ MEGA Schottky barrier rectifier in SOD323 (SC-76) package

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## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage		–	20	V
$I_F$	continuous forward current	$T_{sp} \leq 55\text{ °C}$	–	2	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$	–	7	A
$I_{FSM}$	non-repetitive peak forward current	$t = 8\text{ ms}$ square wave	–	9	A
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C
$T_{amb}$	operating ambient temperature		–65	+150	°C

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	notes 1 and 2	450	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	notes 2 and 3	210	K/W
$R_{th(j-s)}$	thermal resistance from junction to solder point	note 4	90	K/W

### Notes

1. Refer to SOD323 (SC-76) standard mounting conditions.
2. For Schottky barrier diodes thermal runaway has to be considered, as in some applications, the reverse power losses  $P_R$  are a significant part of the total power losses. Nomograms for determination of the reverse power losses  $P_R$  and  $I_F$  (AV) rating will be available on request.
3. Device mounted on a on an FR4 printed-circuit board with copper clad 10 x 10 mm.
4. Soldering point of cathode tab.

## ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$V_F$	forward voltage	see Fig.2; note 1			
		$I_F = 0.01\text{ A}$	200	220	mV
		$I_F = 0.1\text{ A}$	265	290	mV
		$I_F = 1\text{ A}$	380	430	mV
$I_R$	reverse current	$V_R = 5\text{ V}$ ; see Fig.3	15	50	$\mu\text{A}$
		$V_R = 10\text{ V}$	20	80	$\mu\text{A}$
		$V_R = 20\text{ V}$	50	200	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 5\text{ V}$ ; $f = 1\text{ MHz}$ ; see Fig.4	55	70	pF

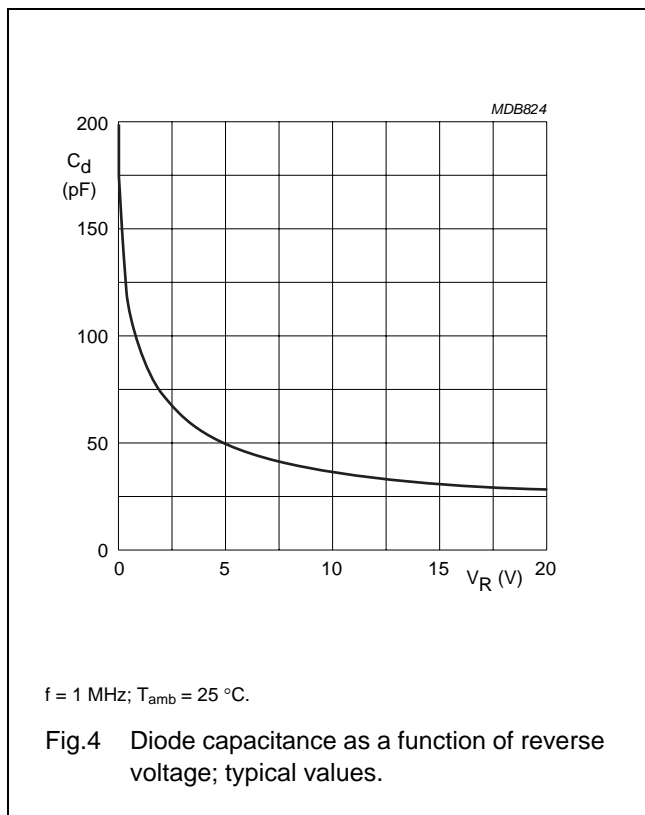
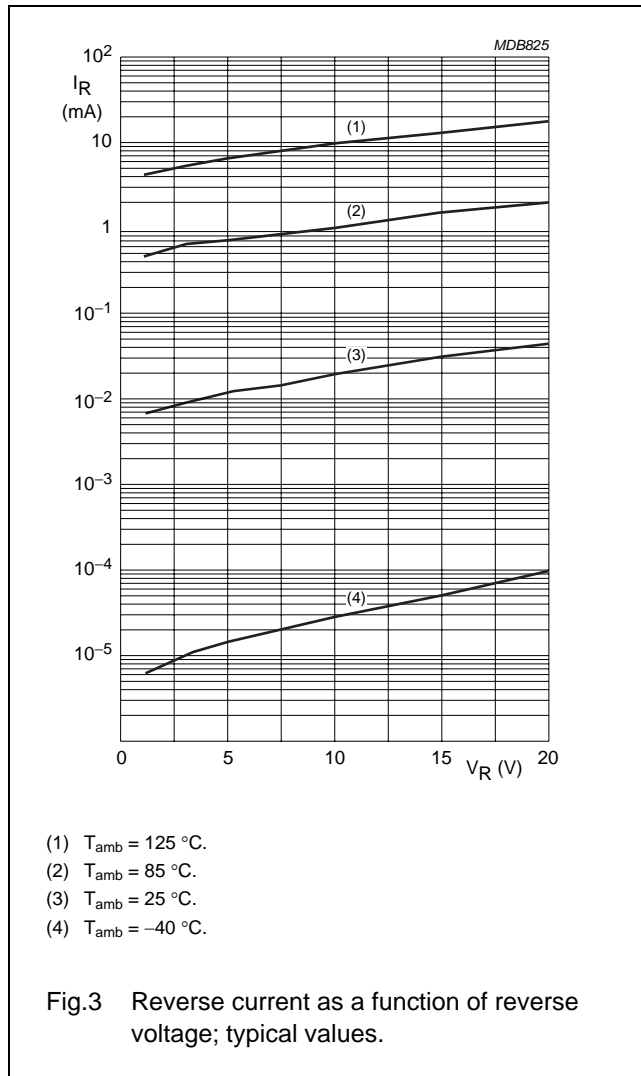
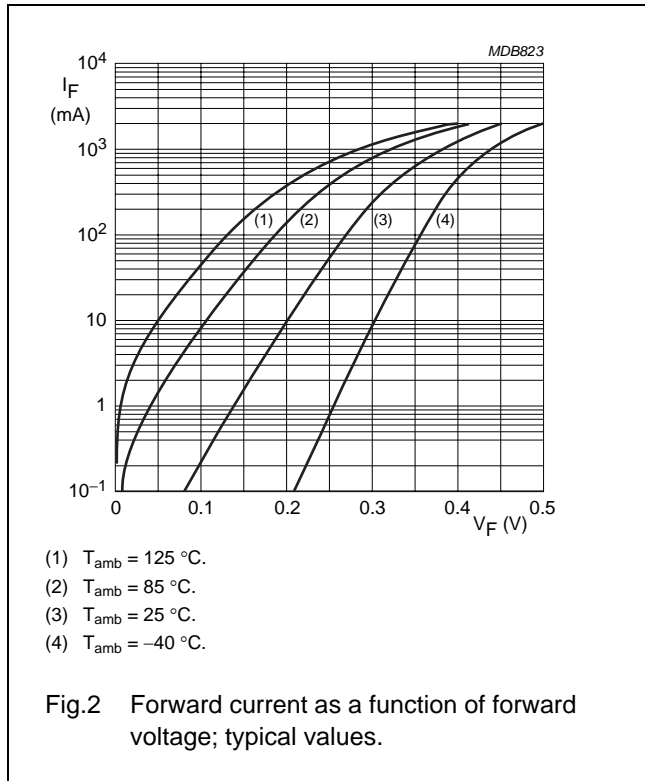
### Note

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

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GRAPHICAL DATA



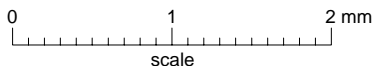
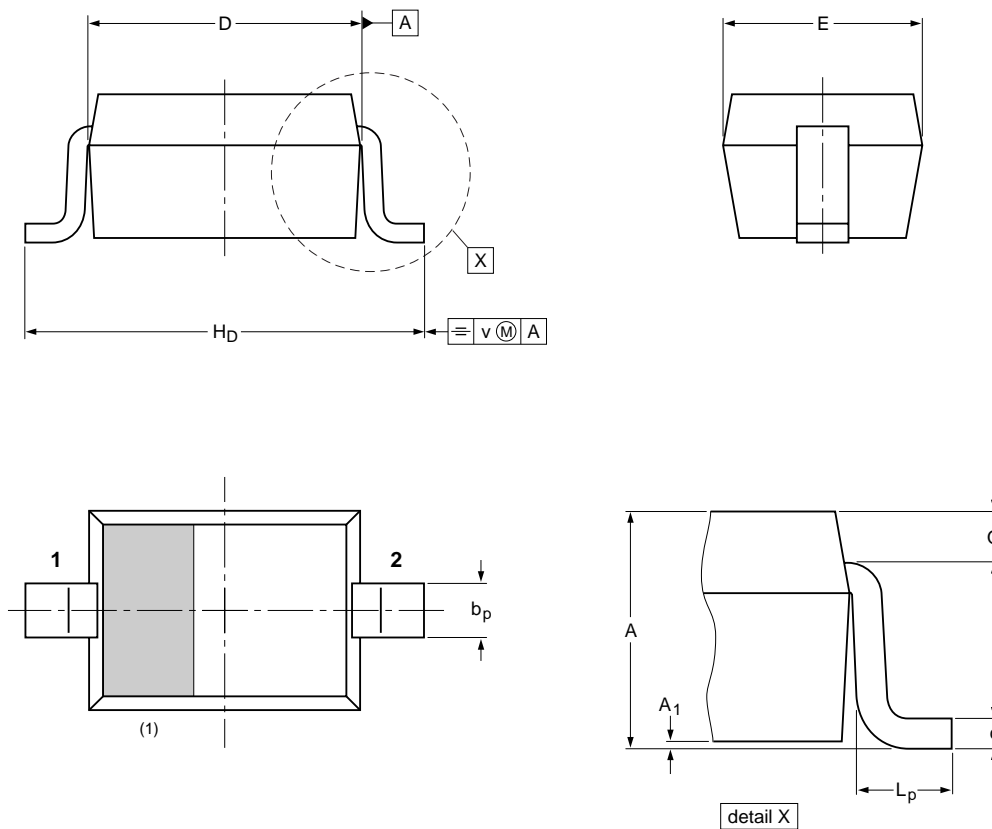
20 V, 2 A very low  $V_F$  MEGA Schottky barrier rectifier in SOD323 (SC-76) package

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PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	H <sub>D</sub>	L <sub>p</sub>	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		<del>03-12-17</del> 06-03-16

# 20 V, 2 A very low $V_F$ MEGA Schottky barrier rectifier in SOD323 (SC-76) package

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## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

## Notes

1. Please consult the most recently issued document before initiating or completing a design.
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# ***NXP Semiconductors***

## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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